

IN THE CLAIMS

1. (Currently Amended) A wiring board comprising:  
an electronic component;  
an embedding resin having a dielectric constant of less than or equal to about 5 and  $\tan\delta$  of less than or equal to about 0.08; and  
a substrate in which a build-up layer formed by laminating an insulating and a wiring layer in alternate fashion is formed ~~[[on]]~~ above said embedding resin,  
wherein, said electronic component is embedded in said embedding resin.
2. (Original) The wiring board according to claim 1, wherein said embedding resin comprises carbon black in an amount of less than or equal to about 1.4 mass%.
3. (Original) The wiring board according to claim 1, wherein said embedding resin comprises a thermosetting resin as a resin component and at least one inorganic filler.
4. (Original) The wiring board according to claim 3, wherein said thermosetting resin is at least one of a bisphenol-type epoxy resin, a naphthalene-type epoxy resin, a phenol-novolak-type epoxy resin, or a cresol-novolak-type epoxy resin.
5. (Original) The wiring board according to claim 1, wherein said embedding resin assumes a color having a base color tone of black, blue, green, red, orange, yellow, or violet.

6. (Currently Amended) The wiring board according to claim 1,  
wherein the substrate is formed on at least one surface of a core substrate; and  
an opening is formed so as to penetrate at least one of said core substrate and said build-up layer,  
wherein said electronic component is placed in the opening and embedded ~~by means of~~ in  
said embedding resin.

7. (Canceled without prejudice or disclaimer)